

FINAL VERSION



**Environmental testing –
Part 2-58: Tests – Test Td: Test methods for solderability, resistance to
dissolution of metallization and to soldering heat of surface mounting devices
(SMD)**

CONTENTS

FOREWORD.....	5
1 Scope.....	7
2 Normative references	7
3 Terms and definitions	8
4 Grouping of soldering processes and related test severities	9
5 Test equipment.....	10
5.1 Solder bath	10
5.2 Reflow equipment	10
6 Test Td ₁ : Solderability of terminations.....	11
6.1 Object and general description of the test	11
6.2 Specimen preparation	11
6.3 Accelerated ageing	11
6.4 Initial measurements.....	11
6.5 Method 1: Solder bath.....	11
6.5.1 Solder bath.....	11
6.5.2 Solder and flux	11
6.5.3 Test procedure and conditions.....	12
6.6 Method 2: Reflow.....	14
6.6.1 Reflow equipment.....	14
6.6.2 Solder paste	14
6.6.3 Test substrates.....	14
6.6.4 Test procedure	14
6.6.5 Reflow temperature profile for Test Td ₁	15
6.6.6 Test conditions	16
7 Test Td ₂ : Resistance to soldering heat.....	16
7.1 Object and general description of the test	16
7.2 Specimen preparation.....	16
7.3 Preconditioning.....	16
7.4 Initial measurements.....	16
7.5 Method 1: Solder bath.....	17
7.5.1 Solder bath.....	17
7.5.2 Solder and flux	17
7.5.3 Test procedure and conditions.....	17
7.6 Method 2: Reflow.....	19
7.6.1 Reflow equipment.....	19
7.6.2 Solder paste	19
7.6.3 Test substrates.....	19
7.6.4 Test procedure and conditions.....	19
8 Test Td ₃ : Dewetting and resistance to dissolution of metallization.....	21
8.1 Object and general description of the test	21
8.2 Specimen preparation.....	21
8.3 Initial measurements.....	22
8.4 Method 1: Solder bath.....	22
8.4.1 Solder bath.....	22
8.4.2 Solder and flux	22

8.4.3	Test procedure and conditions	22
8.5	Method 2: Reflow	22
8.5.1	Reflow equipment	22
8.5.2	Specimen	22
8.5.3	Solder paste	22
8.5.4	Flux	22
8.5.5	Reflow profile	22
8.5.6	Placement of the specimen	23
8.5.7	Application of the reflow profile	23
8.5.8	Evaluation	23
9	Final measurements	23
9.1	Flux removal	23
9.2	Recovery conditions	23
9.3	Evaluation	23
9.3.1	Wetting	23
9.3.2	Dewetting	24
9.3.3	Resistance to soldering heat	25
9.3.4	Resistance to dissolution of metallization	25
10	Information to be given in the relevant specification	25
10.1	General	25
10.2	Solderability	25
10.3	Resistance to soldering heat, dewetting and resistance to dissolution of metallization	26
Annex A (normative)	Criteria for visual examination	27
A.1	Evaluation of wetting	27
A.1.1	General	27
A.1.2	Criteria for wetting	27
A.1.3	Additional criteria for wetting, method 2	28
A.2	Evaluation of dewetting, method 2	29
Annex B (informative)	Guidance	30
B.1	General	30
B.2	Limitations	30
B.3	Choice of severity	30
B.3.1	Test Td ₁ : Solderability by solder bath method	30
B.3.2	Test Td ₂ : Resistance to soldering heat – Solder bath method	31
B.3.3	Test Td ₂ : Resistance to soldering heat – Reflow method	31
B.3.4	Immersion attitude	32
B.3.5	Test Td ₃ : Dewetting and resistance to dissolution of metallization for 30 s at 260 °C	32
Annex C (normative)	Application of the test methods to through hole reflow soldering components (THR)	33
C.1	Solderability	33
C.2	Resistance to soldering heat	33
C.3	Dewetting	33
C.4	Criteria for evaluation	33
Annex X (informative)	Cross reference for references to the prior revision of this specification	34
	Bibliography	36

Figure 1 – Examples of immersion attitudes.....	13
Figure 2 – Reflow temperature profile for solderability	15
Figure 3 – Examples of immersion attitude.....	18
Figure 4 – Reflow temperature profile for resistance to soldering heat	20
Figure 5 – Example for placement of a specimen to a test substrate	23
Figure 6 – Identification of areas on metallic termination.....	24
Figure A.1 – Evaluation of wetting.....	28
Figure A.2 – Evaluation of dewetting.....	29
Table 1 – Grouping of soldering processes and typical test severities – Overview.....	10
Table 2 – Solder alloy and flux for test Td ₁	2
Table 3 – Solderability – Test conditions and severity, solder bath method	14
Table 4 – Solder paste specification	14
Table 5 – Solderability – Test conditions – Method 2: Reflow	16
Table 6 – Resistance to soldering heat – Test conditions and severity, solder bath method	19
Table 7 – Resistance to soldering heat – Test conditions and severity, reflow method	21
Table 8 – Dewetting and resistance to dissolution of metallization – Test conditions and severity, solder bath method	22
Table B.1 – Test conditions.....	31
Table C.1 – Test conditions for solderability test.....	33

INTERNATIONAL ELECTROTECHNICAL COMMISSION

ENVIRONMENTAL TESTING –

Part 2-58: Tests – Test Td: Test methods for solderability, resistance to dissolution of metallization and to soldering heat of surface mounting devices (SMD)

FOREWORD

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This Consolidated version of IEC 60068-2-58 bears the edition number 4.1. It consists of the fourth edition (2015-03) [documents 91/1222/FDIS and 91/1250/RVD] and its amendment 1 (2017-07) [documents 91/1445/FDIS and 91/1451/RVD]. The technical content is identical to the base edition and its amendment.

This Final version does not show where the technical content is modified by amendment 1. A separate Redline version with all changes highlighted is available in this publication.

International Standard IEC 60068-2-58 has been prepared by IEC technical committee 91: Electronics assembly technology.

This fourth edition constitutes a technical revision.

This edition includes the following significant technical changes with respect to the previous edition:

- the addition of Sn-Bi low temperature solder alloy;
- the addition of several reflow test conditions in Table 7 – Resistance to soldering heat – Test conditions and severity, reflow method;
- introduction of reflow test method for Test Td₃: Dewetting and resistance to dissolution of metallization;
- implementation of guidance for the choice of a test severity in Clause B.3.

This publication has been drafted in accordance with the ISO/IEC Directives, Part 1.

A list of all parts in the IEC 60068, published under the general title *Environmental testing*, can be found on the IEC website.

The committee has decided that the contents of the base publication and its amendment will remain unchanged until the stability date indicated on the IEC web site under "<http://webstore.iec.ch>" in the data related to the specific publication. At this date, the publication will be

- reconfirmed,
- withdrawn,
- replaced by a revised edition, or
- amended.

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ENVIRONMENTAL TESTING –

Part 2-58: Tests – Test Td: Test methods for solderability, resistance to dissolution of metallization and to soldering heat of surface mounting devices (SMD)

1 Scope

This part of IEC 60068 outlines test Td, applicable to surface mounting devices (SMD).

This document provides procedures for determining the solderability, resistance to dissolution of metallization and resistance to soldering heat of devices in applications using solder alloys, which are eutectic or near eutectic tin lead (Pb), or lead-free alloys.

The procedures use either a solder bath or reflow method and are applicable only to specimens or products designed to withstand short term immersion in molten solder or limited exposure to reflow systems.

The solder bath method is applicable to SMDs designed for flow soldering and SMDs designed for reflow soldering when the solder bath (dipping) method is appropriate.

The reflow method is applicable to the SMD designed for reflow soldering, to determine the suitability of SMDs for reflow soldering and when the solder bath (dipping) method is not appropriate.

The objective of this standard is to ensure solderability of component lead or termination. In addition, test methods are provided to ensure that the component body can resist against the heat load to which it is exposed during soldering.

This standard covers tests Td₁, Td₂ and Td₃ as listed below:

Number of Td	Test	Method
Td ₁	Solderability of terminations	Method 1: Solder bath Method 2: Reflow
Td ₂	Resistance to soldering heat	Method 1: Solder bath Method 2: Reflow
Td ₃	Dewetting and resistance to dissolution of metallization	Method 1: Solder bath Method 2: Reflow

NOTE 1 For specific components other test methods may exist.

NOTE 2 Test Td does not apply to printed wiring board (PWB), see IEC 61189-3.

NOTE 3 Specific through-hole devices (where the device supplier has specifically documented support for reflow soldering) are also included in this standard.

2 Normative references

The following documents, in whole or in part, are normatively referenced in this document and are indispensable for its application. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 60068-1, *Environmental testing – Part 1: General and guidance*

IEC 60068-2-20:2008, *Environmental testing – Part 2-20: Tests – Test T: Test methods for solderability and resistance to soldering heat of devices with leads*